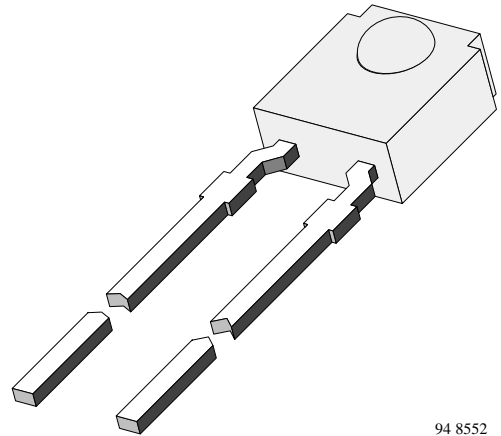

GaAlAs IR Emitting Diode in Side View Miniature Package

Description

TSSA 2500 is a high efficiency infrared emitting diode in GaAlAs on GaAlAs technology, molded in a clear, untinted miniature plastic side view package.

A small spherical lens provides an improved radiant intensity..

The diode is case compatible to the TEST2500 phototransistor, allowing the user to assemble his own optical interrupters.



94 8552

Features

- High radiant power
- Suitable for high pulse current operation
- Side view emitter for miniature design
- Angle of half intensity $\varphi = \pm 25^\circ$
- Peak wavelength $\lambda_p = 875 \text{ nm}$
- High reliability

Applications

High power infrared emitter in miniature light barriers, transmissive or reflective sensors.

Infrared remote control and free air transmission systems with small package size requirements in combination with PIN photodiodes or phototransistors.

Package matching with phototransistor TEST 2500.

Because of the reduced radiance absorption in glass at the wavelength of 875 nm, TSSA 2500 is suitable for systems with panes in the transmission range between emitter and detector.

Absolute Maximum Ratings

 $T_{amb} = 25^{\circ}\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		V_R	5	V
Forward Current		I_F	100	mA
Peak Forward Current	$t_p/T=0.5, t_p=100\ \mu\text{s}$	I_{FM}	200	mA
Surge Forward Current	$t_p=100\ \mu\text{s}$	I_{FSM}	1.5	A
Power Dissipation		P_V	170	mW
Junction Temperature		T_j	100	$^{\circ}\text{C}$
Operating Temperature Range		T_{amb}	-55...+100	$^{\circ}\text{C}$
Storage Temperature Range		T_{stg}	-55...+100	$^{\circ}\text{C}$
Soldering Temperature	$t \leq 5\text{sec}, 2\ \text{mm from case}$	T_{sd}	260	$^{\circ}\text{C}$
Thermal Resistance Junction/Ambient		R_{thJA}	450	K/W

Basic Characteristics

 $T_{amb} = 25^{\circ}\text{C}$

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	$I_F = 100\ \text{mA}, t_p = 20\ \text{ms}$	V_F		1.5	1.8	V
Forward Voltage	$I_F = 1.5\ \text{A}, t_p = 100\ \mu\text{s}$	V_F		3.2		V
Temp. Coefficient of V_F	$I_F = 100\ \text{mA}$	TK_{VF}		-1.6		mV/K
Reverse Current	$V_R = 5\ \text{V}$	I_R			100	μA
Junction Capacitance	$V_R = 0\ \text{V}, f = 1\ \text{MHz}, E = 0$	C_j		20		pF
Radiant Intensity	$I_F = 100\ \text{mA}, t_p = 20\ \text{ms}$	I_e	3.5	10		mW/sr
Radiant Intensity	$I_F = 1.5\ \text{A}, t_p = 100\ \mu\text{s}$	I_e		120		mW/sr
Radiant Power	$I_F = 100\ \text{mA}, t_p = 20\ \text{ms}$	ϕ_e		15		mW
Temp. Coefficient of ϕ_e	$I_F = 100\ \text{mA}$	TK_{ϕ_e}		-0.7		%/K
Angle of Half Intensity		φ		± 25		deg
Peak Wavelength	$I_F = 100\ \text{mA}$	λ_p		875		nm
Spectral Bandwidth	$I_F = 100\ \text{mA}$	$\Delta\lambda$		80		nm
Temp. Coefficient of λ_p	$I_F = 100\ \text{mA}$	TK_{λ_p}		0.2		nm/K
Rise Time	$I_F = 100\ \text{mA}$	t_r		600		ns
Rise Time	$I_F = 1.5\ \text{A}$	t_r		300		ns
Fall Time	$I_F = 100\ \text{mA}$	t_f		600		ns
Fall Time	$I_F = 1.5\ \text{A}$	t_f		300		ns

Typical Characteristics ($T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified)

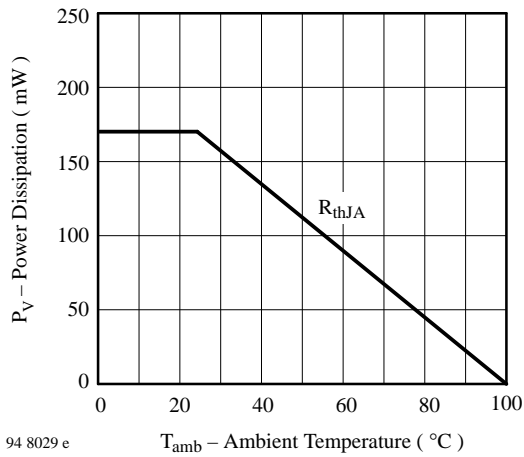


Figure 1 : Power Dissipation vs. Ambient Temperature

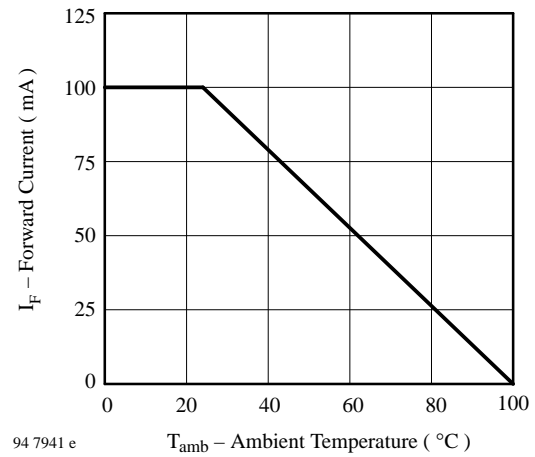


Figure 2 : Forward Current vs. Ambient Temperature

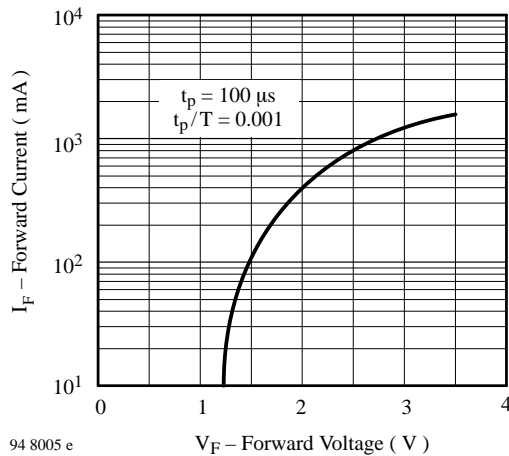


Figure 3 : Forward Current vs. Forward Voltage

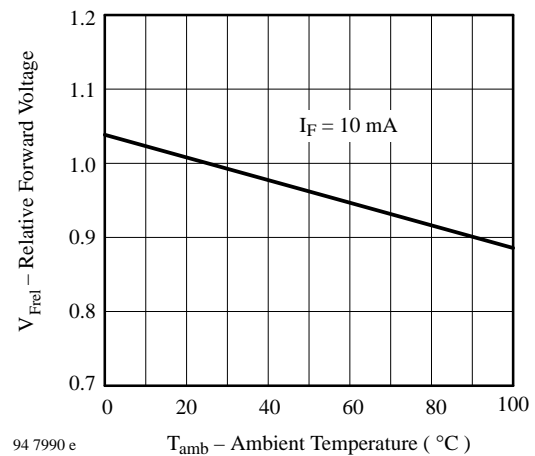


Figure 4 : Relative Forward Voltage vs. Ambient Temperature

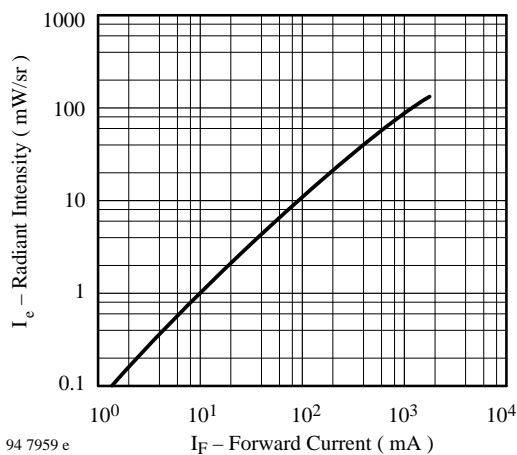


Figure 5 : Radiant Intensity vs. Forward Current

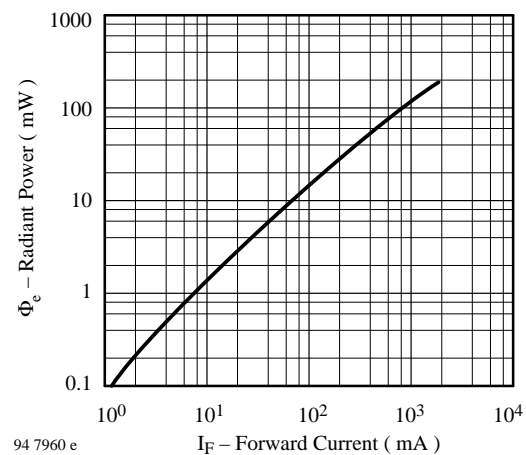


Figure 6 : Radiant Power vs. Forward Current

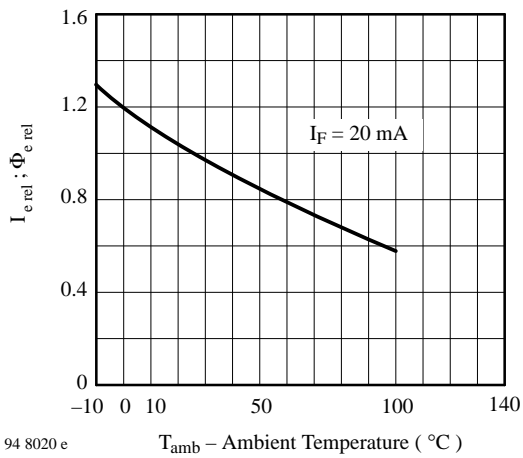


Figure 7 : Rel. Radiant Intensity/Power vs. Ambient Temperature

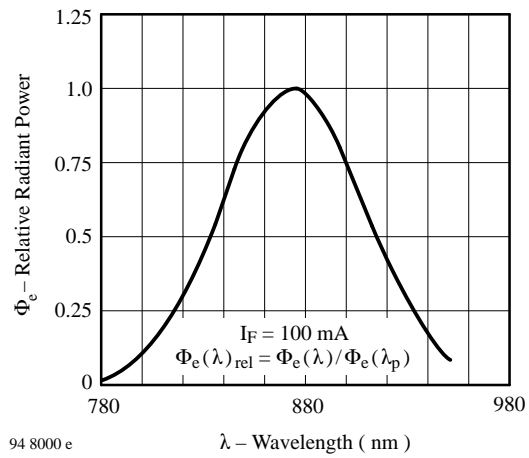


Figure 8 : Relative Radiant Power vs. Wavelength

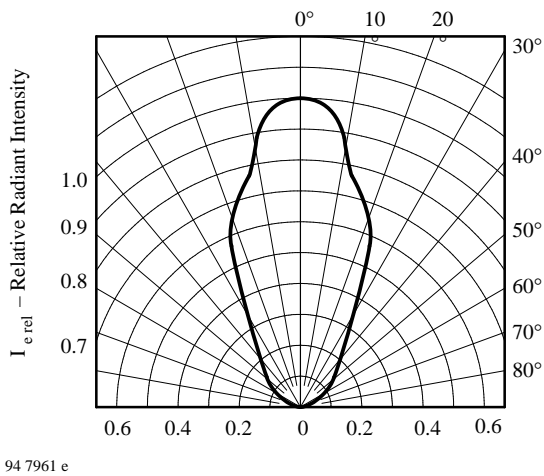
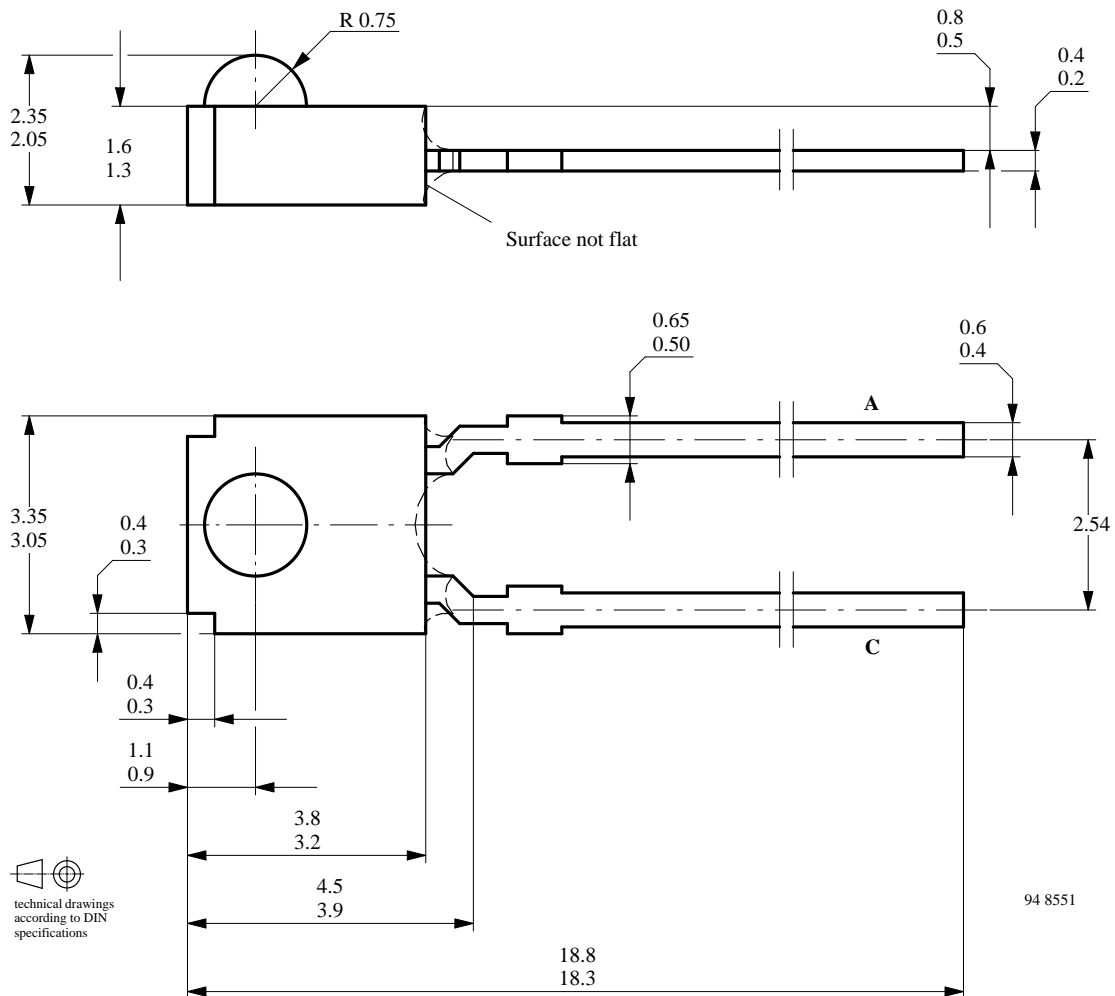


Figure 9 : Relative Radiant Intensity vs. Angular Displacement

Dimensions in mm



We reserve the right to make changes to improve technical design without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany
 Telephone: 49 (0)7131 67 2831, Fax Number: 49 (0)7131 67 2423